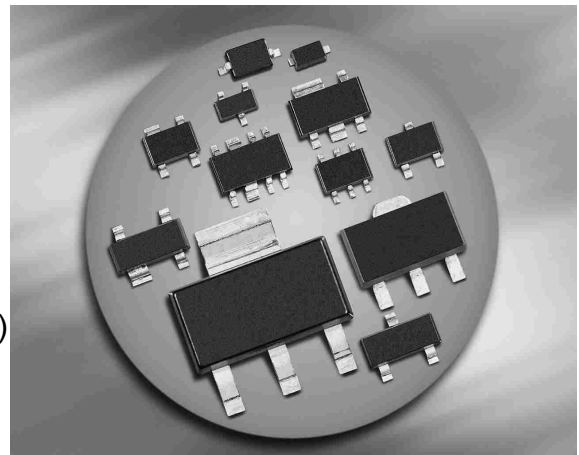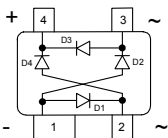**Low VF Schottky Diode Array**

• Reverse voltage: 40 V

• Forward current: 0.2 A

• Small diode quad array for polarity independance, reverse polarity protection and low loss bridge rectification

• Very low forward voltage: 0.55 @ 0.1 A (per diode)

• Fast switching

• Pb-free (ROHS compliant) package

• Qualified according AEC Q101

BAS4002A-RPP

Type	Package	Configuration	Marking
BAS4002A-RPP	SOT143	bridge	E9s

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage[1]	V_R	40	V
Peak reverse voltage[1]	V_{RM}	40	
RMS reverse voltage[1]	$V_{R(RMS)}$	28	
Forward current[1], $T_S \leq 124$ °C	I_F	200	mA
Non-repetitive peak surge forward current ($t \leq 10$ ms)	I_{FSM}	2	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ...150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[2]	R_{thJS}	$\leq$ 130	K/W

[1]For T_A > 25°C the derating of V_R and I_F has to be considered.

[2]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

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**Electrical Characteristics** at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current[1] (per diode)	I_R				µA
V_R = 30 V		-	-	2	
V_R = 40 V		-	-	10	
Forward voltage[1] [2] (per diode)	V_F				V
I_F = 10 mA		-	0.39	0.44	
I_F = 60 mA		-	0.49	0.55	
I_F = 100 mA		-	0.55	0.62	
I_F = 200 mA		-	0.69	0.79	
AC Characteristics					
Diode capacitance (per diode)	C_T	-	2	5	pF
V_R = 5 V, f = 1 MHz					

[1]Pulsed test, t_p = 300 µs; D = 0.01

[2]When used as shown for Reverse Polarity Protection (RPP, see page 4), the voltage available to the circuit being protected will be two diode drops below the power supply voltage. In other words, the supply current will pass through two diodes.
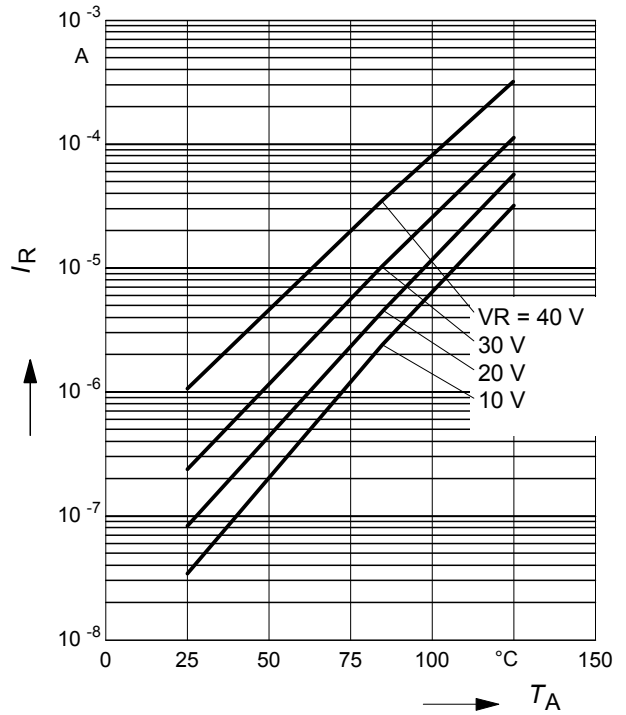
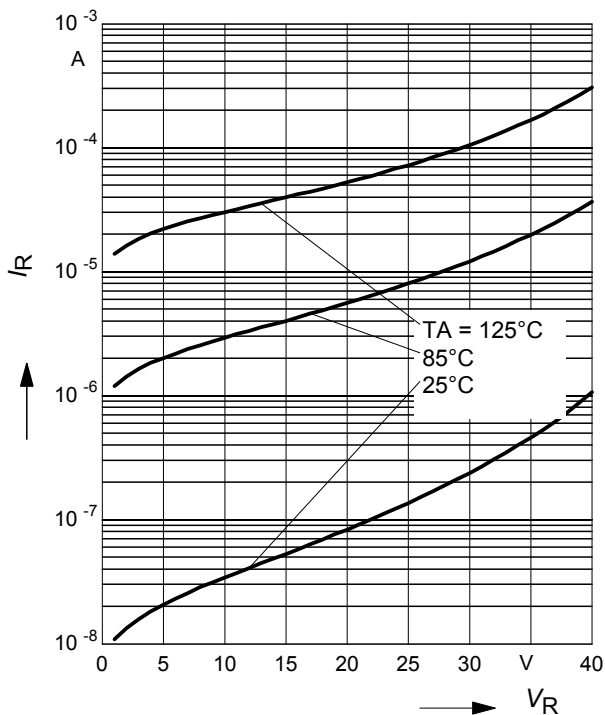**Diode capacitance** $C_T = f(V_R)$

f = 1MHz (per diode)
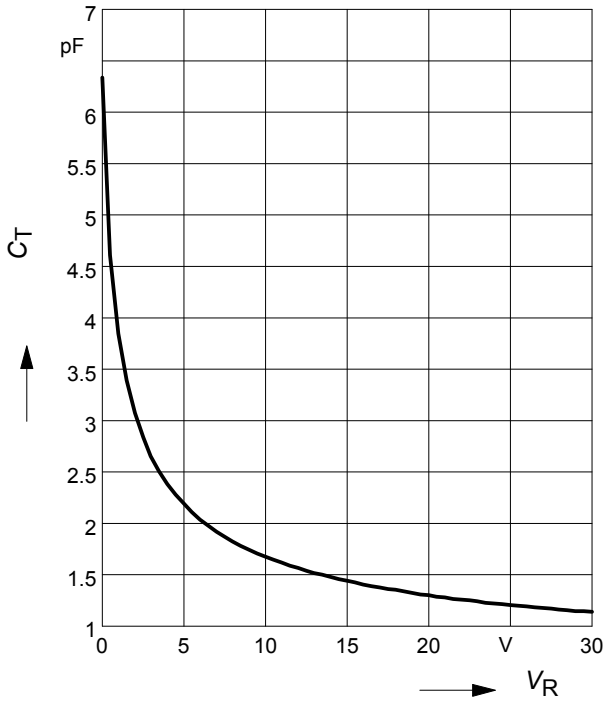
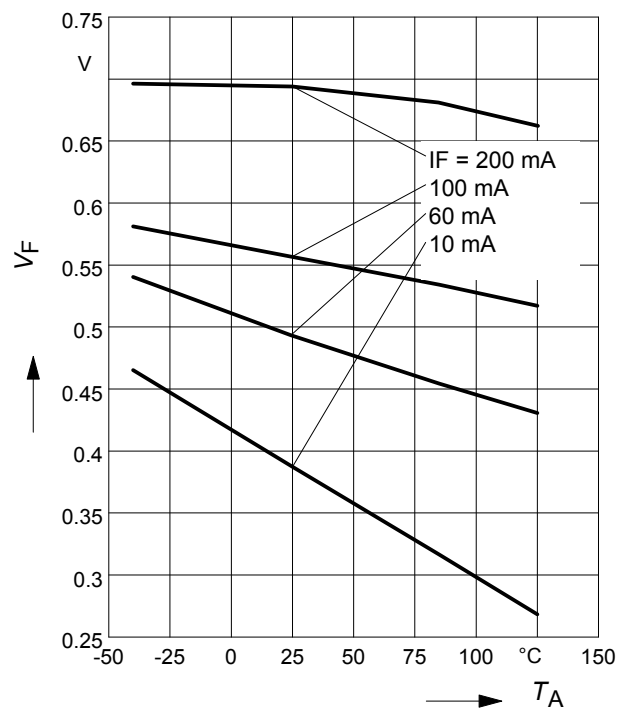**Reverse current** $I_R = f(T_A)$

V_R = Parameter (per diode)

Reverse current $I_R = f(V_R)$

T_A = Parameter (per diode)

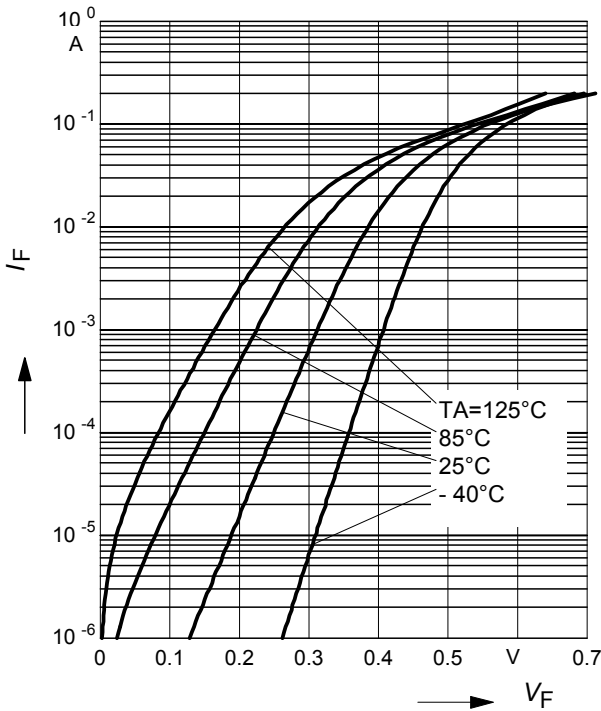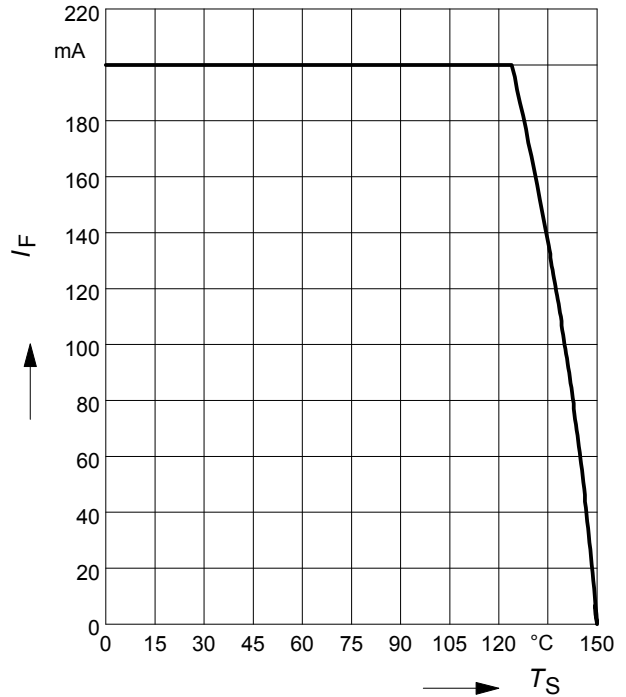**Forward Voltage** $V_F = f(T_A)$

I_F = Parameter (per diode)

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Forward current $I_F = f(V_F)$

(per diode)

Forward current $I_F = f(T_S)$

BAS4002-RPP

Graph left:
- Y-axis: I_F (A), from 10^{-6} to 10^0
- X-axis: V_F (V), from 0 to 0.7
- Curves labeled: TA=125°C, 85°C, 25°C, -40°C

Graph right:
- Y-axis: I_F (mA), from 0 to 220
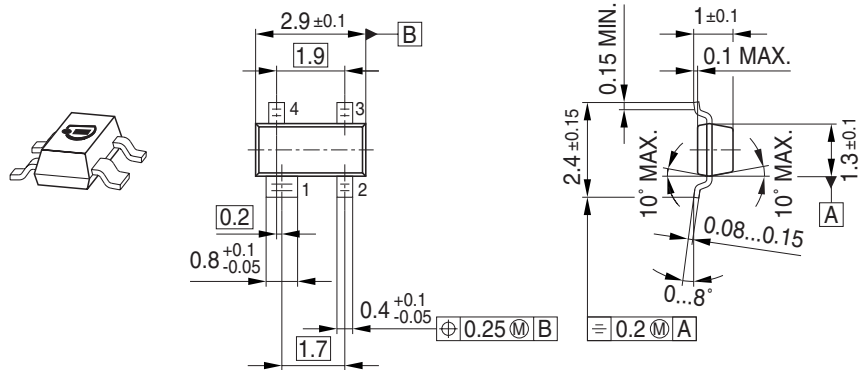- X-axis: T_S (°C), from 0 to 150
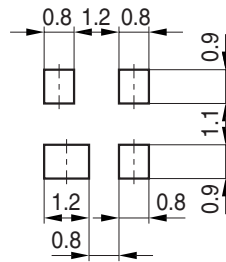
Application example BAS4002A-RPP

Advanced Reverse Polarity Protection(RPP): due to diode orientation, circuit at the right will be protected from damage and will also function normally in the event reverse polarity is applied to pins 2 and 3 of the BAS4002A-RPP.
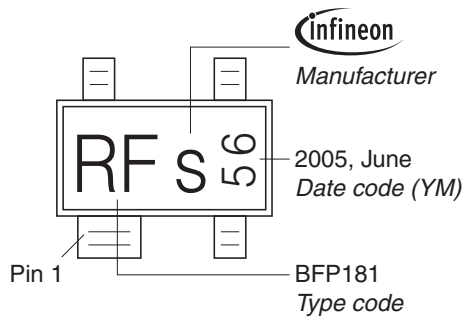
Ground /
+Vs

DC Plug to
power supply

+Vs /
Ground

2 1

3 4

Ground

Reverse polarity
protected circuit

+Vs
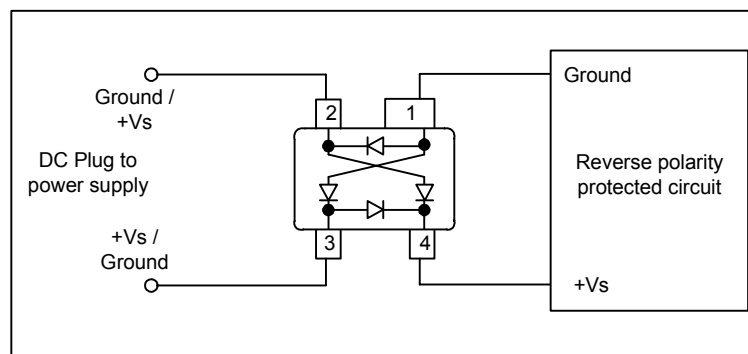
Package Outline

Foot Print

Marking Layout (Example)

Manufacturer

2005, June
Date code (YM)

Pin 1

BFP181
Type code

Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel
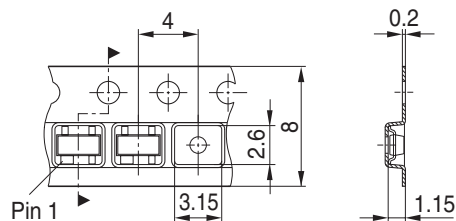
Pin 1

Attention please!

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